

AbstractASSEMBLY AND METHOD FOR IMPROVED SINGULATION

- 5 A punch and die assembly for singulating an IC unit from a substrate, the assembly comprising an array of punches a guide block having opposed first and second faces with a plurality of elongate channels corresponding to each punch extending from said first to second face; a die block for supporting said substrate, said die block having an array of punching zones at which the punches bear so as to singulate all or a portion of a
- 10 peripheral edge of said IC units from the substrate.

Figure 1



162162



G00002